

CLH01

○ Switching Mode Power Supply Applications

- Forward voltage: $V_{FM} = 0.98 \text{ V (Max.)}$
- Average forward current: $I_{F(AV)} = 3 \text{ A}$
- Repetitive peak reverse voltage: $V_{RRM} = 200 \text{ V}$
- Surface-mount package
L-FLAT™ (Toshiba package name)

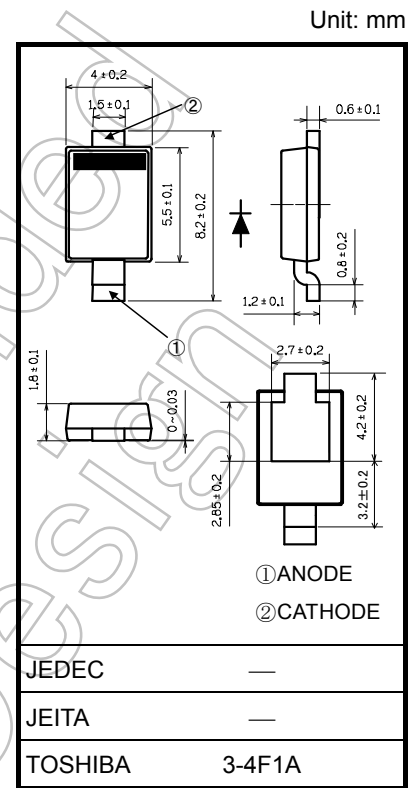
Absolute Maximum Ratings ($T_a = 25^\circ\text{C}$)

| Characteristics | Symbol | Rating | Unit |
|---|-------------|------------|------|
| Repetitive peak reverse voltage | V_{RRM} | 200 | V |
| Average forward current | $I_{F(AV)}$ | 3 (Note 1) | A |
| Peak one cycle surge forward current (non-repetitive) | I_{FSM} | 60 (50 Hz) | A |
| Junction temperature | T_j | -40~150 | °C |
| Storage temperature range | T_{stg} | -40~150 | °C |

Note 1: $T_l = 132^\circ\text{C}$ Rectangular waveform : ($\alpha = 180^\circ$)

Note 2: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).



Weight: 0.15 g (typ.)

Electrical Characteristics ($T_a = 25^\circ\text{C}$)

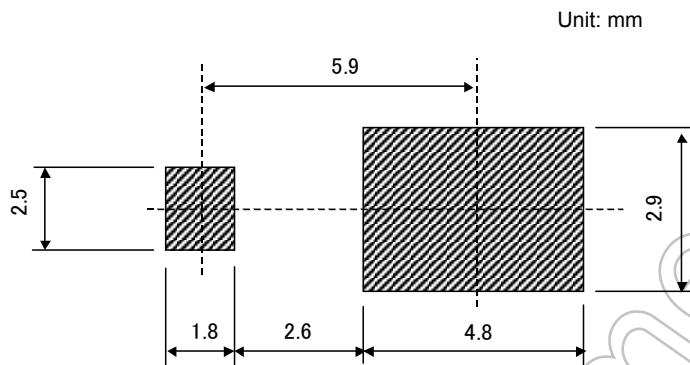
| Characteristics | Symbol | Test Condition | Min | Typ. | Max | Unit |
|--|---------------|---|-----|------|------|------|
| Peak forward voltage | $V_{FM(1)}$ | $I_{FM} = 0.7 \text{ A}$ (pulse test) | — | 0.76 | — | V |
| | $V_{FM(2)}$ | $I_{FM} = 1.0 \text{ A}$ (pulse test) | — | 0.78 | — | |
| | $V_{FM(3)}$ | $I_{FM} = 3.0 \text{ A}$ (pulse test) | — | 0.88 | 0.98 | |
| Repetitive peak reverse current | I_{RRM} | $V_{RRM} = 200 \text{ V}$ (pulse test) | — | — | 10 | μA |
| Reverse recovery time | t_{rr} | $I_F = 2 \text{ A}$, $di/dt = -50 \text{ A}/\mu\text{s}$ | — | — | 35 | ns |
| Forward recovery time | t_{fr} | $I_F = 1.0 \text{ A}$ | — | — | 100 | ns |
| Thermal resistance (junction to ambient) | $R_{th(j-a)}$ | Device mounted on a glass-epoxy board (board size:50mm x 50mm) (board thickness:1.6t) (soldering land) Cathode:5.7mm x 6.2mm Anode :4.5mm x 3.4mm | — | — | 100 | °C/W |
| Thermal resistance (junction to lead) | $R_{th(j-l)}$ | — | — | — | 5 | °C/W |

Start of commercial production
2004-11

Marking

| Abbreviation Code | Part No. |
|-------------------|----------|
| H01 | CLH01 |

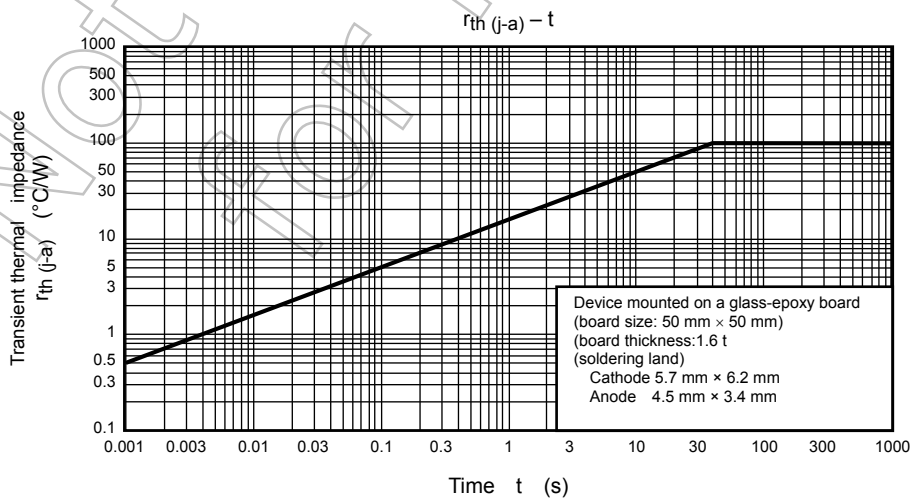
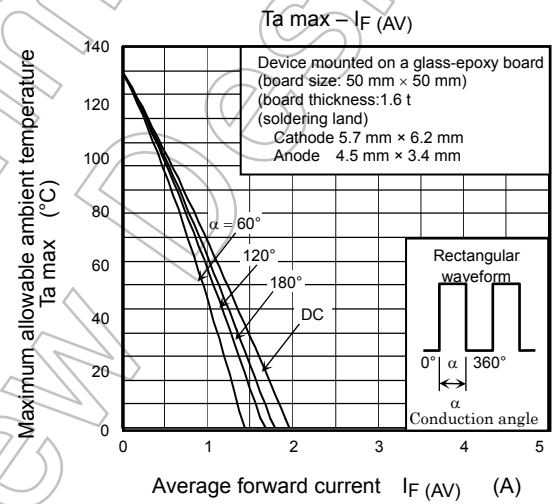
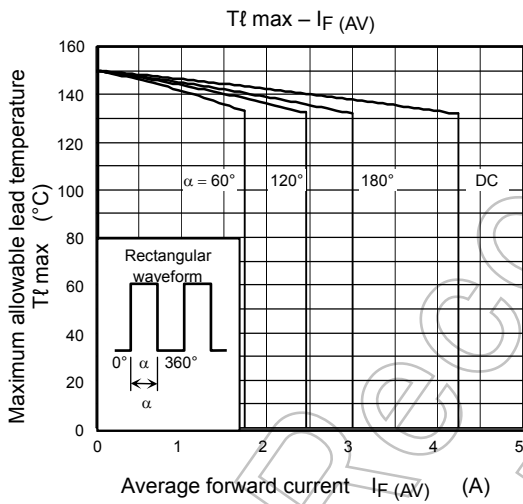
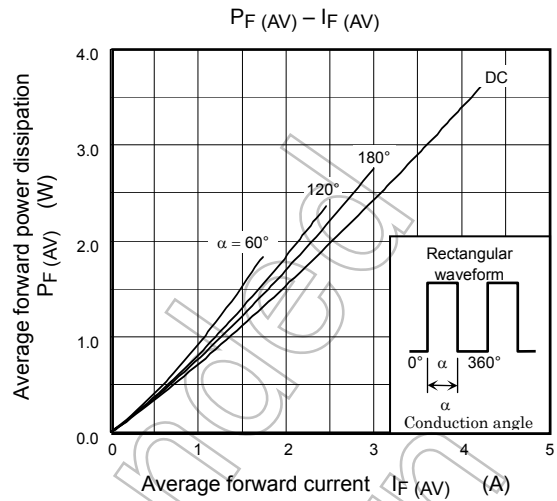
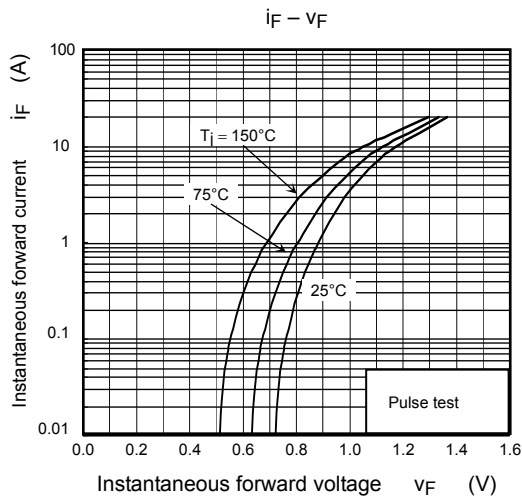
Standard Soldering Pad

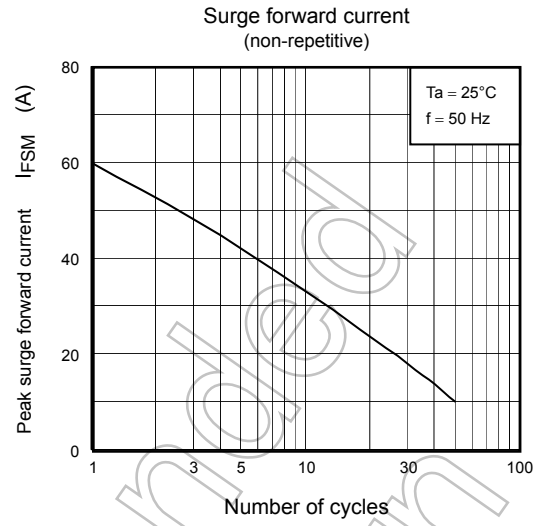
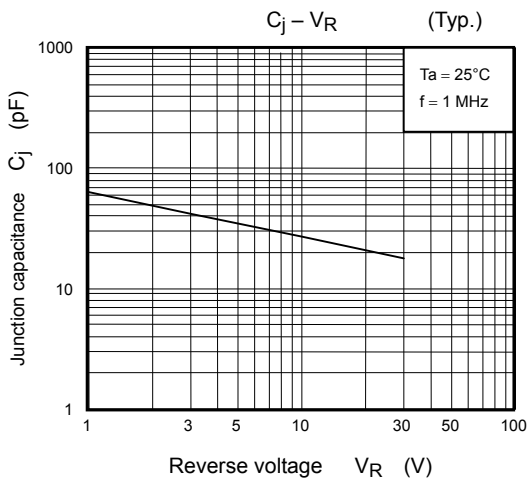


Handling Precautions

- The absolute maximum rating denotes the absolute maximum ratings, which are rated values that must not be exceeded during operation, even for an instant. The following are the general derating methods that we recommend for designing a circuit incorporating this device:

 - V_{RRM} : Use this rating with reference to (1) above. The V_{RRM} has a temperature coefficient of $0.1\%/^{\circ}C$. Take this temperature coefficient into account when designing a device at low temperature.
 - $I_{F(AV)}$: We recommend that the worst case current be no greater than 80% of the absolute maximum rating of $I_{F(AV)}$ and that T_j be below $120^{\circ}C$. When using this device, take the margin into consideration by using an allowable $T_a(\max)$ - $I_{F(AV)}$ curve.
 - I_{FSM} : This rating specifies the non-repetitive peak current. This applies to abnormal operation only. When using a device, design a circuit board and a soldering land size to match the appropriate thermal resistance value.
 - I_{FSM} : This rating specifies the non-repetitive peak current. This applies to abnormal operation only. When using the device, design the circuit board and the soldering land size to match the appropriate thermal resistance value.
 - T_j : Derate this rating when using the device to ensure high reliability. We recommend that the device be used at a T_j of below $120^{\circ}C$.
- The thermal resistance between junction and ambient varies depending on the mounting condition of the device. When using the device, design the circuit board and the soldering land size to match the appropriate thermal resistance value.
- See the Rectifiers databook for further information information.





Not Recommended for New Design

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